

BSP-THREAD-MOUNT Standard / Miniature Reed Relay Datasheet

MiRelay model-level engineering reference for RFQ, cross-reference review and preliminary design-in. Company: SHR AUTOSENSOR TECH LIMITED. Website: www.reed-relay.com. Email: sales@reed-relay.com. Phone/WhatsApp: +86 137 6157 1029.



Product image is representative. Marking, terminal details and accessories can vary by exact option and customer drawing.

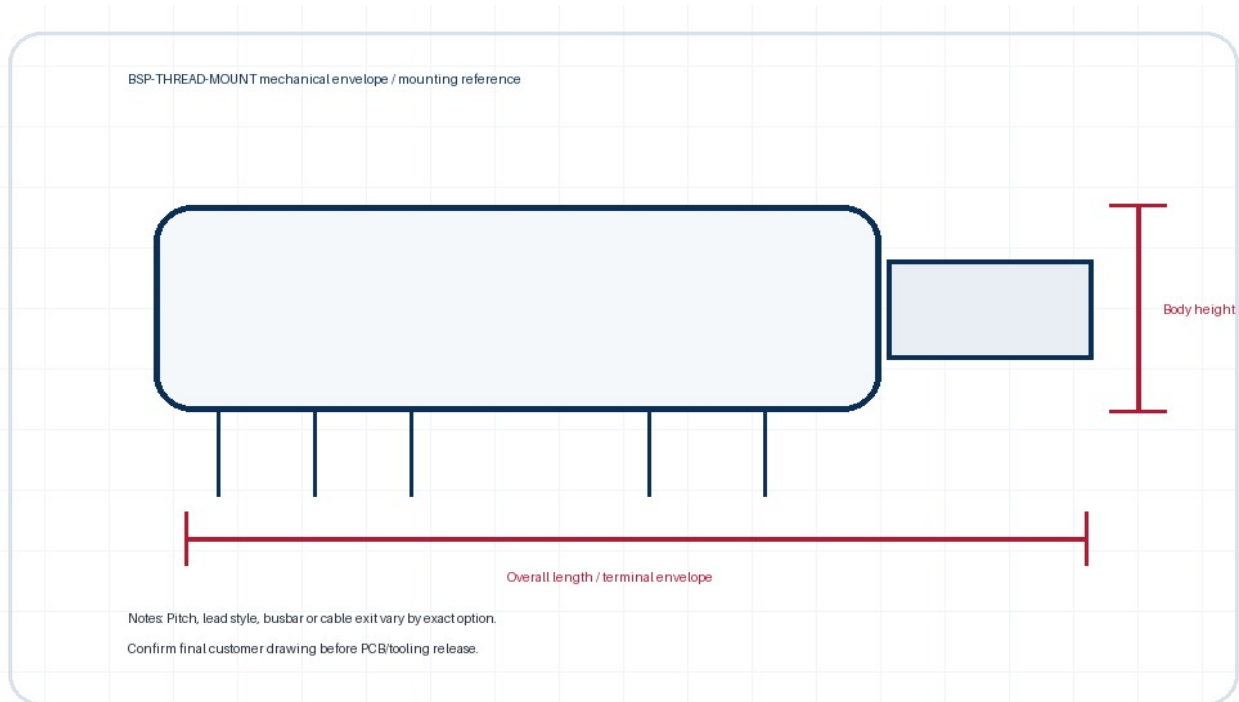
Key selection parameters

Parameter	Engineering note
Package	SIP / MSIP / VSIP / DIP / SMD options
Signal level	Low-level analog and instrumentation switching
Coil voltage	5 / 12 / 24 VDC common options
Applications	ICT/ATE matrix, instruments, telecom, security, robotics

Ordering code interpretation

Code block	Meaning
BSP-THREAD-MOUNT	Model or series identifier
Options	Confirm exact ratings, package and terminal drawing before production

Mechanical envelope and drawing guidance



This drawing is an engineering envelope illustration prepared for selection and RFQ discussions. Use the final signed MiRelay drawing for PCB layout, mounting holes, busbar design, wire/cable exit, creepage/clearance and tooling release.

RFQ / design-in checklist

Package density and land pattern
Contact form and signal level
Coil power budget
Shield/diode/low-EMF option
Cleaning and insulation target

Required information for quotation

Please send target model or competitor part number, electrical ratings, load type, coil/control voltage, package limits, environmental requirements, sample quantity and annual forecast to sales@reed-relay.com. Attach drawings or PCB constraints when available.

Important notice

Preliminary engineering document. Specifications are derived from MiRelay family references and local product assets; they are not a substitute for final approval drawings, signed datasheets, customer validation or safety certification review. Mercury-wetted, high-voltage, medical, EV and PV applications require application-specific validation.